



International Conference on Powder and Powder Metallurgy, 2023, Kyoto

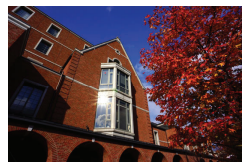
Date: Oct. 16 (Mon) - Oct. 18 (Wed), 2023 Venue: Doshisha University, Kambaikan

2nd Announcement JSPMIC2023

Organized by Japan Society of Powder and Powder Metallurgy (JSPM)

DATE : October 16 (Mon)~ October 18 (Wed), 2023

VENUE : Doshisha University, Kambaikan, Kyoto, Japan



Submission Deadline of Application Form for the Presentation:

30th June (Fri), 2023, 24:00 <JST>

Submission Application Form for the Presentation

Participants wishing to make a presentation in the technical program are cordially invited to **submit a short abstract for the program committee** in English **not later than 30 June (Fri), 2023, 24:00 <JST>**

Submission URL <https://jspmic.conf.it.atlas.jp/login>

All submitted papers will be reviewed and allocated to oral or poster sessions by the Program Committee, based on the authors' choices. The notification of acceptance will be delivered to authors by e-mail by the beginning of August 2023.

Technical Session Categories

A-1: Synthesis, Modification and Properties of Functional Particle

A-2: Powder Handling and Processing

A-3: Colloidal Dispersion and Processing

B-1: Powder Compaction

B-2: Powder Forging, Rolling, Extrusion

B-3: Spray Forming

B-4: CIP and HIP

B-5: PIM (Powder Injection Molding)

B-6: Additive Manufacturing with Powder Metallurgy

C-1: Sintering and Post Processing

C-2: Spark Plasma Sintering and Field/Current Assisted Process

C-3: Testing and Evaluation

C-4: Quality and Environment Control

C-5: Powder Manufacturing and Treatment

C-6: Mechanical Alloying

C-7: Modeling and Simulation

D-1: Iron and Steel Materials

D-2: Non-ferrous Materials and High Entropy Alloys

D-3: Refractory and High Temperature Materials

D-4: Automotive Applications

D-5: Aerospace Applications

E-1: Cemented Carbide

E-2: Cermet

E-3: Diamond, CBN, Ceramics

E-4: Hard Coatings

F-1: Soft Magnetic Materials

F-2: Hard Magnetic Materials

F-3: Materials and Devices with Magnetic Functionality

G-1: Composite and Hybrid Materials

G-2: Porous and Cellular Materials

G-3: Friction Materials

G-4: Metallic glasses (Bulk, Rapidly quenched)

G-5: Nano and Ultra-fine Materials

G-6: Optical Materials

G-7: Functionally Graded and Layered Materials

G-8: Bio-Medical Materials

G-9: Ionic Conducting Materials

G-10: Battery and Electrode

G-11: Magnetic, Superconducting, Electric, Dielectric and Thermoelectric Materials

G-12: Electronic Components and Packaging Materials

G-13: Power Electronic Devices

Technical Program

Technical sessions (for oral and poster presentations) are scheduled as listed below. The official language of the conference will be English.

Oral Sessions: 20 minutes will be allocated to each paper including discussion time. All presentations must be given in English and are limited to one speaker for each presentation.

Poster Sessions: Posters given in English will be on display from October 17th, 13:00 to October 18th, 13:00. Authors will be provided core time for one-on-one discussions at the evening of October 17th. Core time will be available drinks and light foods.

Schedule of JSPMIC2023

October 16 (Mon)	From 15:00 to 17:00	Registration Desk Open Get together (in front of the registration desk)
October 17 (Tue)	From 9:00 to 10:30 From 10:50 From 13:00 From 18:00 to 20:00	Opening address and Plenary Talks Technical Sessions (Oral presentation) Technical Sessions (Poster presentation) Poster Core Time
October 18 (Wed)	From 9:00 to 16:00 By 13:00 From 16:00 From 18:00 to 20:00	Technical Sessions (Oral presentation) Technical Sessions (Poster presentation) Plenary Talk Conference Party

Plenary Talk Speakers

October 17 (Tue)	Dr. Vidarsson Hilmar (Höganäs AB, Sweden) Dr. Susanne Norgren (SANDVIK, Sweden)
October 18 (Wed)	Dr. Masato SAGAWA (Daido Steel Co., Ltd., Japan)

Invited Speakers (Tentative)

Jun CHEN	University of Science and Technology Beijing, China
Wei-tin CHEN	National Taiwan University, Taiwan
Yau-Hung CHIOU	You need Technology, China
Shen J. DILLON	University of California Irvine, USA
Swee K. GOH	The Chinese University of Hong Kong, China
Jing-Feng LI	Tsinghua University, China
Takayoshi NAKANO	Osaka University, Japan
Yoshitake MASUDA	National Institute of Advanced Industrial Science and Technology (AIST), Japan
Chung-Hsin LU	National Taiwan University, Taiwan
Ryosuke SENG	National Institute of Advanced Industrial Science and Technology (AIST), Japan
Seiichi SUDA	Shizuoka University, Japan
Hong-Tao SUN	National Institute for Materials Science (NIMS), Japan
Hisao SUZUKI	Shizuoka University, Japan
Ma QIAN	Royal Melbourne Institute of Technology, Australia
Raquel de Oro CALDERON	Institute of Chemical Technologies and Analytics TU Wien, Austria
Kenzo YAMAGUCHI	Tokushima University, Japan
Shaojun WANG	Soochow University, China
Yifeng WANG	Nanjing Technological University, China

Abstract Submission

Submission Deadline of Abstract: September 13 (Wed) 24:00 <JST>

All the authors should submit abstract by using the frame format and converting it into pdf file. You will upload the pdf file through the following URL using your ID and password when you created your account.
<https://jspmfuncyio.confit.atlas.jp/login>

The abstract of the JSPMIC2023 will be released only on its web site on **September 25 (Mon), 2023**. The authors must complete the procedures related to patents by the release date if necessary.

For making the abstract, you should

1. Use A4 size (210mm×297mm), one sheet. You can download the form of the abstract from JSPMIC2023 website.
2. Please confirm the details such as margins, fonts, figures, how to embed fonts on the website.
3. Convert document file to PDF file (Size of PDF file is up to 5MB).
4. Upload your abstract by **September 13th (Wed), 24:00 <JST>, 2023**.
5. Please be sure to use the program number (example:13A-A1-01) that we are informing for the file name.
6. We do not give you proofreading. Please submit a complete document by the author's responsibility.

Award

1) Poster Award: Poster Awards will be given to outstanding poster presentations.

2) JSPMIC2023 Paper Award:

The committee of JSPMIC2023 and the editorial board of the journal of JSPM have decided to **establish "JSPMIC2023 Paper Award"**. The items for the award are as below;

1. The content of the paper is the same as the presentation at JSPMIC2023.
2. The submission of the paper is the same as a paper in the category (2.1.1) of the journal of JSPM below.
<https://www.jspm.or.jp/application/files/5215/4043/4635/GuidelinesForSubmissions.pdf>
3. The period of submission is **from October 19th 2023 to February 29th 2024**.
4. The language is English.
5. The review (judgement) of the paper after the submission is also the same as a paper in the category (2.1.1) of the journal of JSPM (JJSPM).
6. After the paper will be accepted, it will be published on J-Stage online journal of JJSPM that is the open access journal under the CC license (CC BY-NC-ND 4.0 international) and has been selected the Scopus.

Registration

Registration will be available through this web-site from the beginning of August.

Registration Fees

Early-bird (Due: September 22, 2023)	Regular: 50,000 JPY	Student: 10,000 JPY
Late/On-Site	Regular: 60,000 JPY	Student: 12,000 JPY

Accompanying person 10,000 JPY

- Regular registration includes attendance at all Technical Sessions, and Conference party.
- Student registration includes attendance at all Technical Sessions.
- All participants are able to attend at the Autumn Meeting of JSPM, 2023 for free.
- Accompanying person registration includes attendance at the Conference party.
- All participants are advised to pre-register to ensure admission to the conference.

Visa

You must have a valid passport. A visa is required for citizens of countries that do not have visa-exempt agreements with Japan. Please contact the nearest Japanese Embassy or Consulate for visa requirements. If you should require any assistance in preparing documents for visa application, please inform the Secretariat of it when you fill out registration form.

Conference Party

The conference Party will be held at The HEIAN JINGU SHRINE Hall on 18th October (Wed), from 18:00-20:00. The many impressive aspects of the Heian Jingu Shrine such as its vermillion-colored buildings and beautiful white sand emphasize the tradition and prestige at this shrine. The HEIAN JINGU SHRINE Hall is located within the shrine grounds and next to the "Shin-en Garden". In contrast to the magnificent image of the vermillion shrine gate (Torii) and gorgeous shrine buildings, the view of the vast garden gives the venue a calm and quiet atmosphere. At this venue you can see some beautiful autumn foliage in the fall while enjoying exquisite traditional Japanese cuisine that is prepared using in season and local ingredients from Kyoto. We would like you to get a feel for the tradition that continues to be passed down since the Heian period.



Important Dates

Application Form for the Presentation:

30th June (Fri), 2023

Abstract Submission:

13th September (Wed), 2023

Early-bird Registration:

22nd September (Fri), 2023

For any inquiries, please contact:

Secretariat of JSPMIC2023

jspmic2022@jspm.or.jp

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